PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ADG/17/10083
1.3 Title of PCN	Additional Assembly and Test Location in China for Protection devices housed in SOT23/323 packages
1.4 Product Category	Protection devices housed in SOT23/323 packages
1.5 Issue date	2017-02-01

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK WOLINSKI
2.1.2 Phone	+49 89460062287
2.1.3 Email	frank.wolinski@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Richard RENARD
2.1.2 Marketing Manager	Christian NOPPER
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Machines	(Not Defined)	Malaysia (subco 1) – ECOPACK®2 CHINA (subco 2) – ECOPACK®2

4. Description of change

	Old	New
4.1 Description	Malaysia (subco 1) – ECOPACK®2	Malaysia (subco 1) – ECOPACK®2 CHINA (subco 2) – ECOPACK®2
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

5. Reason / motivation for change

5.1 Motivation	This multi-sourcing will increase our manufacturing capacity for a better service on the considered Protection devices housed in the SOT23/323 package.
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

6. Marking of parts / traceability of change

6.1 Description	internal codification and QA number

7. Timing / schedule

7.1 Date of qualification results	2017-01-24
7.2 Intended start of delivery	2017-04-24
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

10083 Public product.pdf 10083 PCN_SOT23_323_Jan'2017.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ESDA25W	
	ESDA6V1L	